

## VCRR P-Channel Enhancement Mode Power MOSFET

### Description

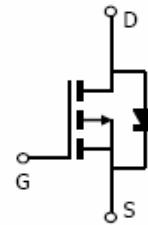
The VCRR60P45K uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### General Features

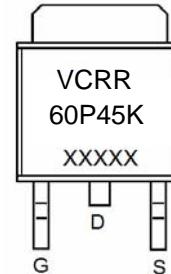
- $V_{DS} = -60V, I_D = -45A$
- $R_{DS(ON)} < 35m\Omega @ V_{GS} = -10V$
- High density cell design for ultra low  $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation

### Application

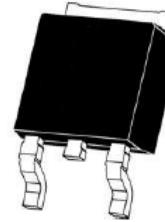
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Schematic diagram



Marking and pin assignment



TO-252-2L top view

### Package Marking and Ordering Information

Device Marking	Device	Device Package
VCRR60P45K		

### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-45	A
Drain Current-Continuous( $T_c=100^\circ C$ )	$I_D (100^\circ C)$	-31.8	A
Pulsed Drain Current	$I_{DM}$	180	A
Maximum Power Dissipation	$P_D$	110	W
Derating factor		0.73	W/ $^\circ C$
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	168	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	$^\circ C$

### Thermal Characteristic

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{\theta JC}$	1.36	$^\circ C/W$
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**Electrical Characteristics ( $T_C=25^\circ\text{C}$  unless otherwise noted)**

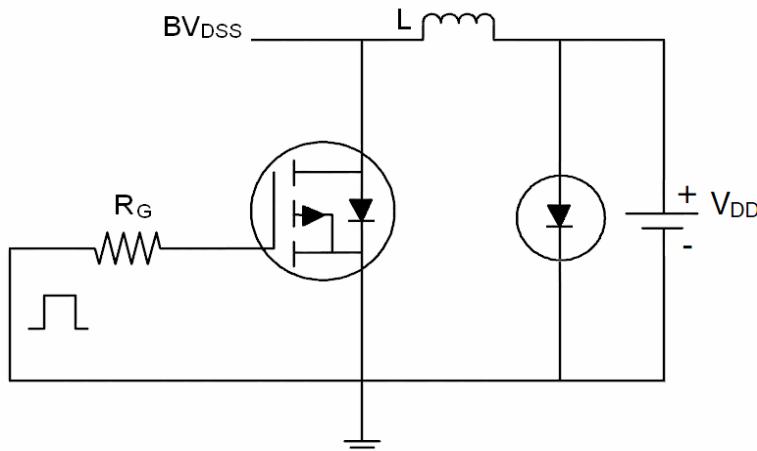
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-60	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=-60\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-2.0	-2.6	-3.5	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-20\text{A}$	-	31	35	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-20\text{A}$	-	20	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	2049	-	PF
Output Capacitance	$C_{\text{oss}}$		-	112.7	-	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	88.7	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=-30\text{V}, I_{\text{D}}=-20\text{A}$ $V_{\text{GS}}=-10\text{V}, R_{\text{GEN}}=3\Omega$	-	13	-	nS
Turn-on Rise Time	$t_r$		-	14	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	39	-	nS
Turn-Off Fall Time	$t_f$		-	15	-	nS
Total Gate Charge	$Q_g$	$V_{\text{DS}}=-30\text{V}, I_{\text{D}}=-20\text{A}, V_{\text{GS}}=-10\text{V}$	-	35.1	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	9	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	7.9	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-20\text{A}$	-	-	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_{\text{S}}$	$T_J = 25^\circ\text{C}, IF = -20\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$ <sup>(Note 3)</sup>	-	-	-45	A
Reverse Recovery Time	$t_{\text{rr}}$		-	-	40	nS
Reverse Recovery Charge	$Q_{\text{rr}}$		-	-	70	nC

**Notes:**

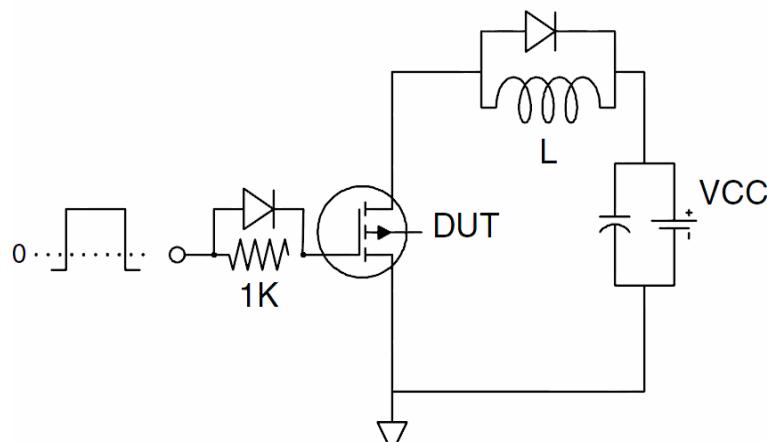
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. E<sub>AS</sub> condition:  $T_j=25^\circ\text{C}, V_{\text{DD}}=-30\text{V}, V_{\text{G}}=-10\text{V}, L=0.5\text{mH}, R_g=25\Omega$

## Test Circuit

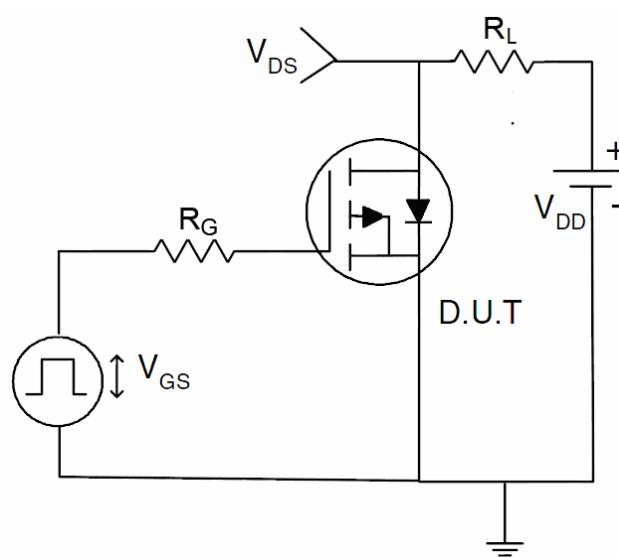
### 1) E<sub>AS</sub> Test Circuit



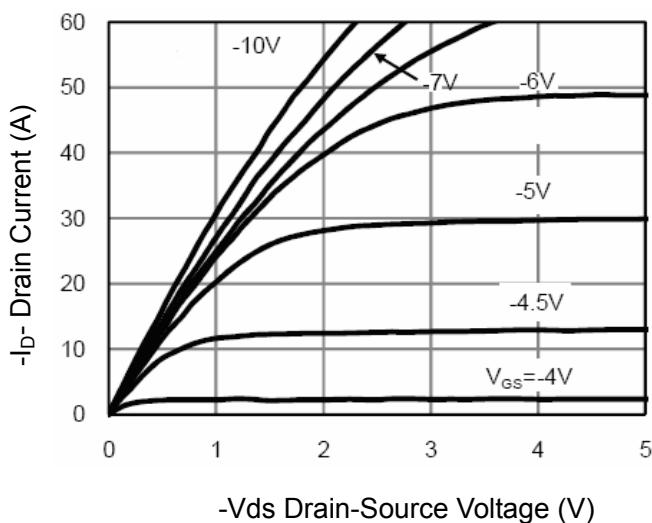
### 2) Gate Charge Test Circuit



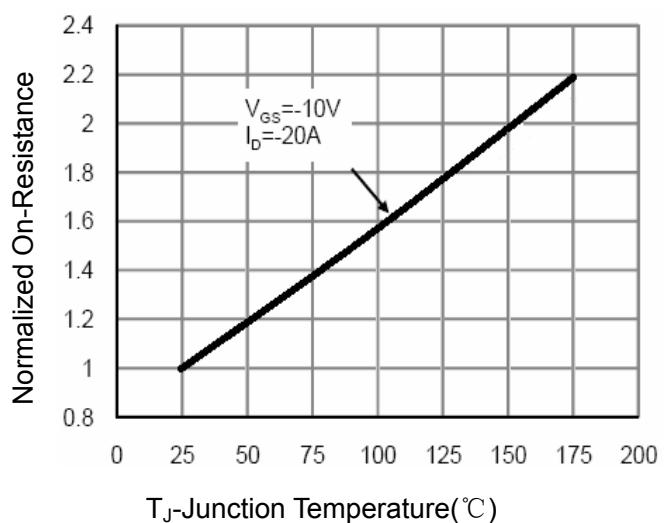
### 3) Switch Time Test Circuit



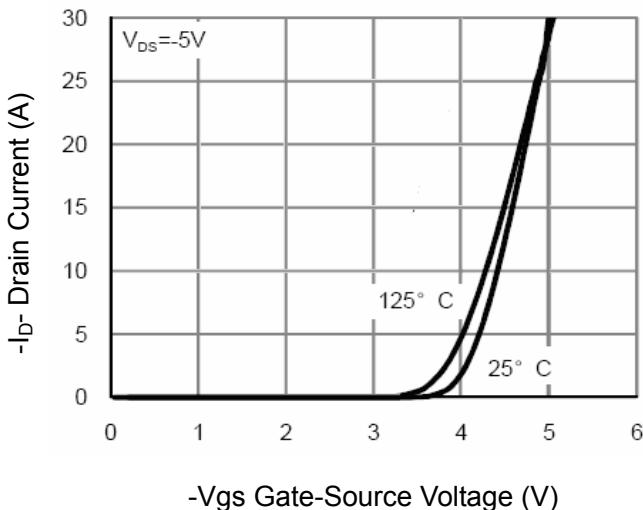
### Typical Electrical and Thermal Characteristics (Curves)



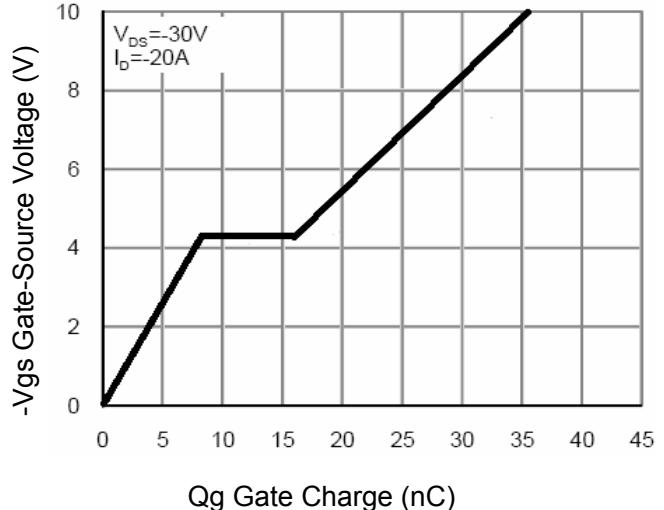
**Figure 1 Output Characteristics**



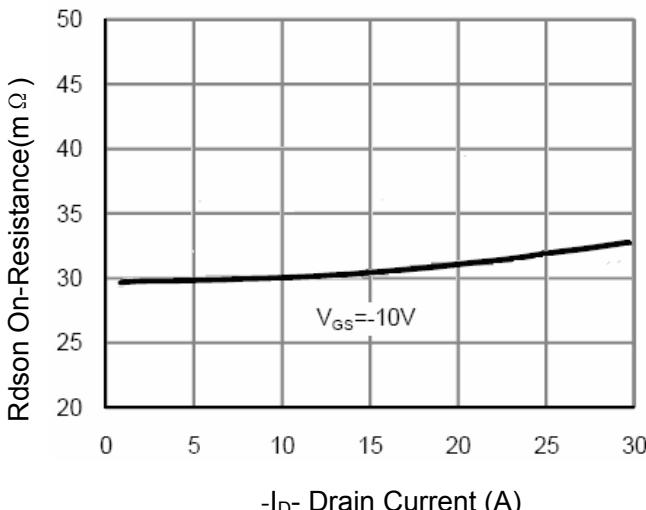
**Figure 4 Rdson-JunctionTemperature**



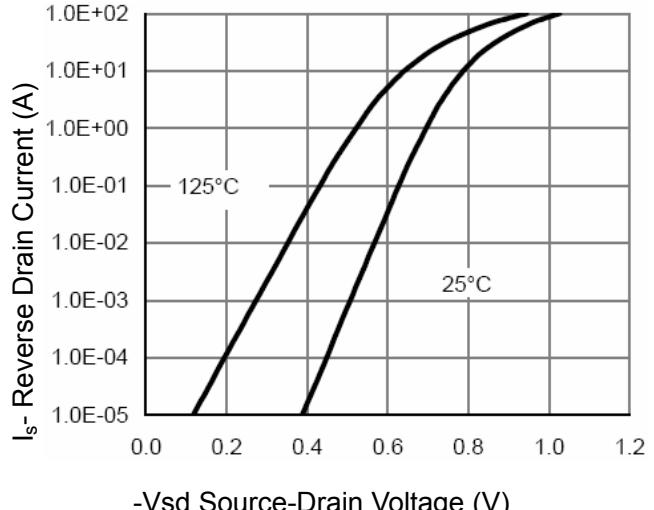
**Figure 2 Transfer Characteristics**



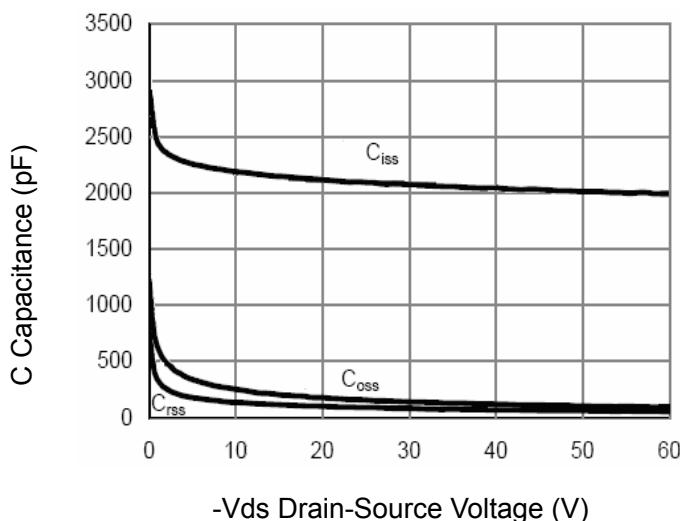
**Figure 5 Gate Charge**



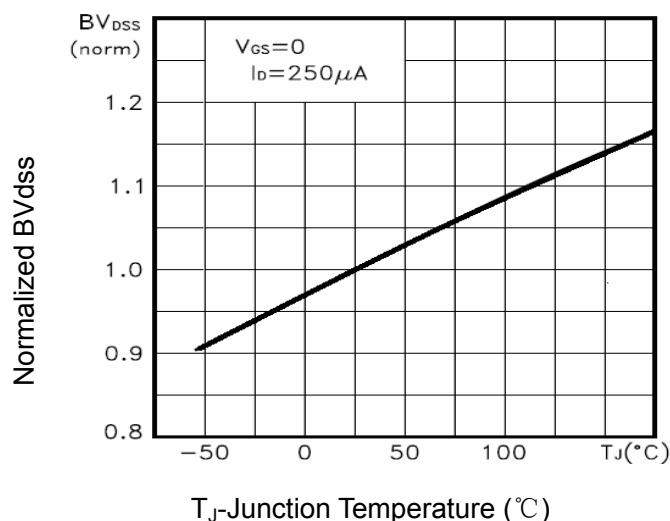
**Figure 3 Rdson- Drain Current**



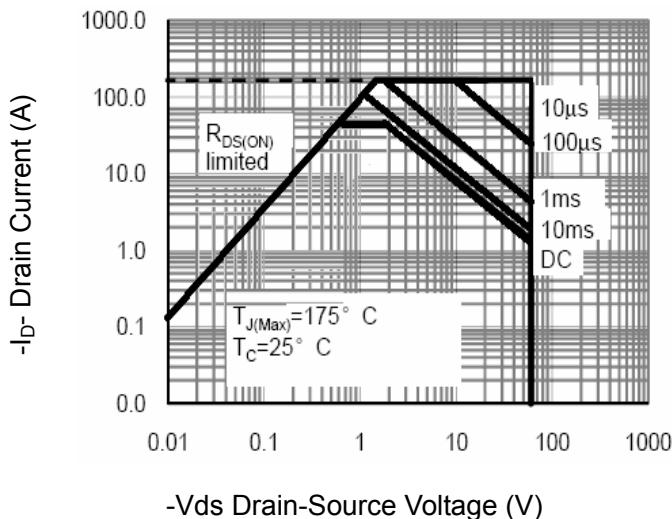
**Figure 6 Source- Drain Diode Forward**



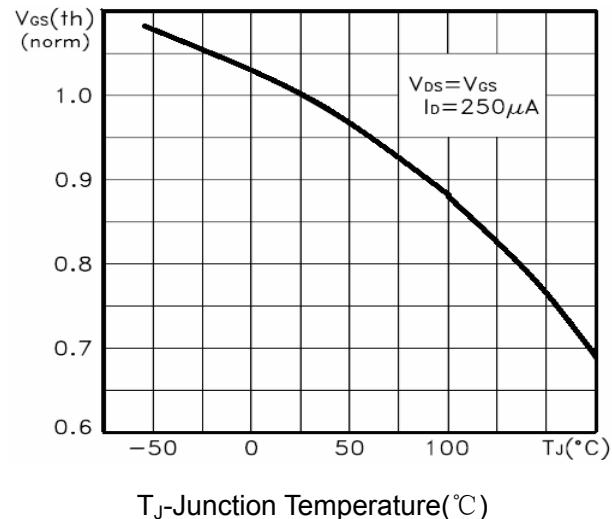
**Figure 7 Capacitance vs Vds**



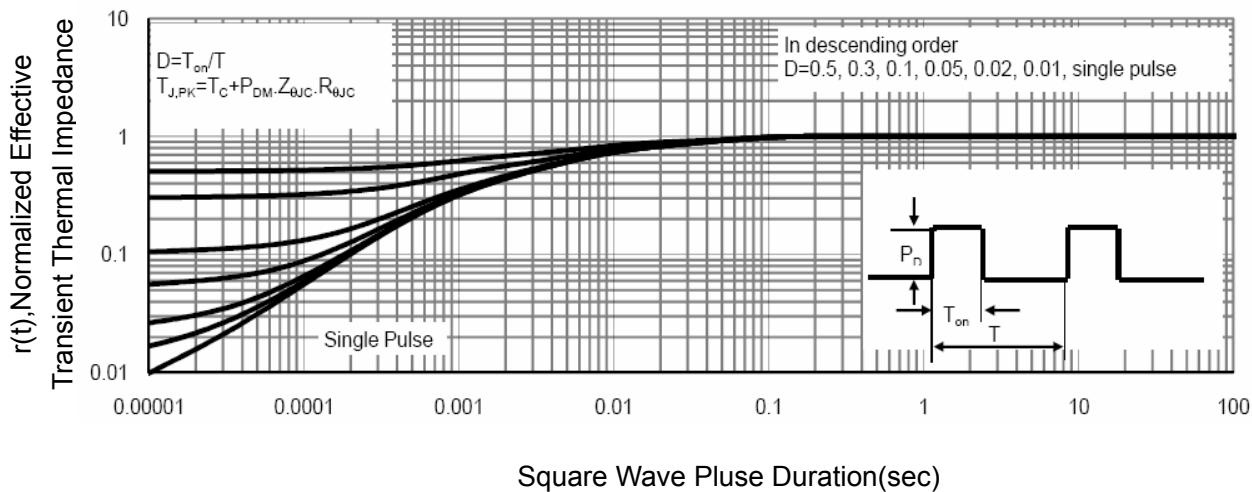
**Figure 9  $BV_{DSS}$  vs Junction Temperature**



**Figure 8 Safe Operation Area**

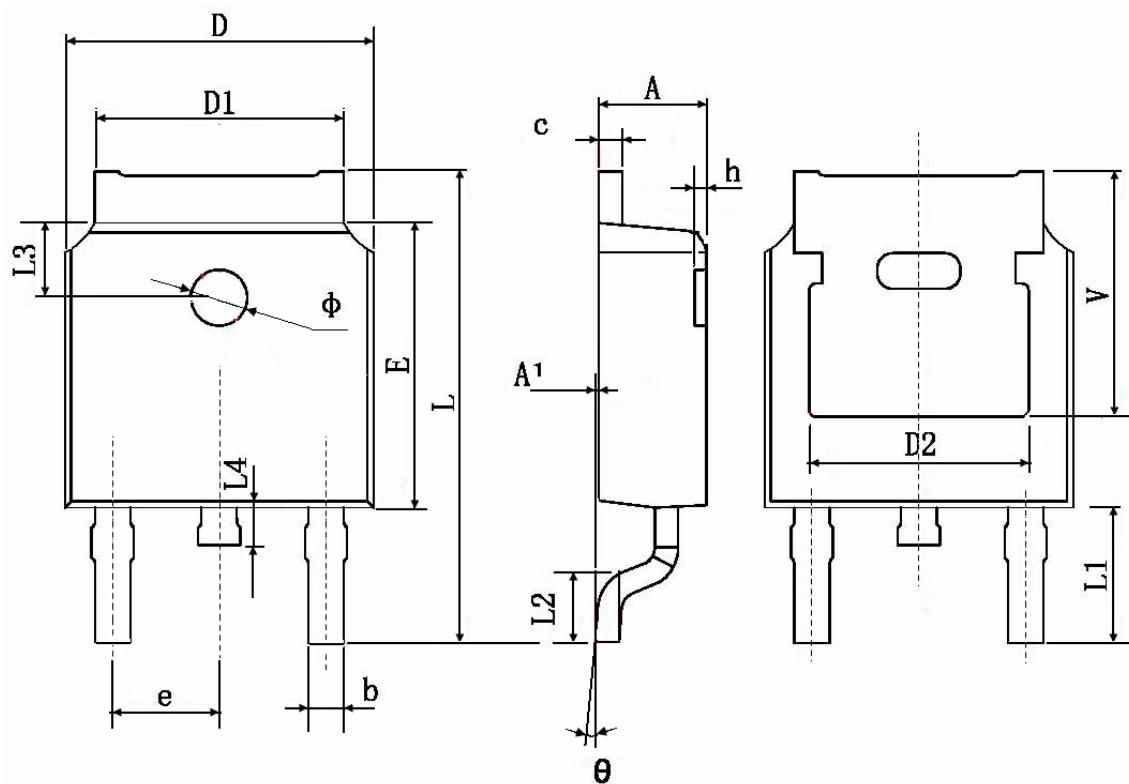


**Figure 10  $V_{GS(\text{th})}$  vs Junction Temperature**



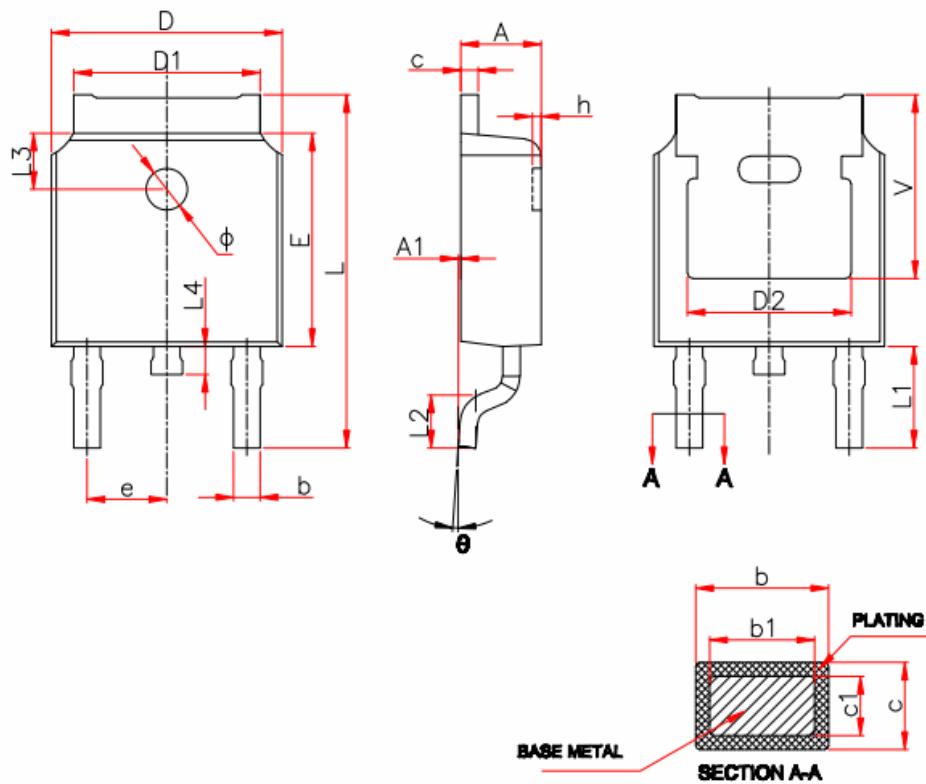
**Figure 11 Normalized Maximum Transient Thermal Impedance**

## TO-252(C) Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

## TO-252(E) Package Information



Symbol	Millimeters	
	Min.	Max.
A	2.20	2.40
A1	0.00	0.13
b	0.66	0.86
b1	0.73	0.79
c	0.46	0.58
c1	0.50	0.52
D	6.50	6.70
D1	5.10	5.46
D2	4.83 REF.	
E	6.00	6.20
e	2.19	2.39
L	9.80	10.40
L1	2.90 REF.	
L2	1.40	1.70
L3	1.60 REF.	
L4	0.60	1.00
$\phi$	1.10	1.30
$\theta$	0°	8°

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